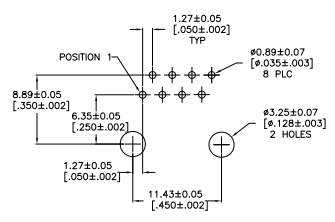
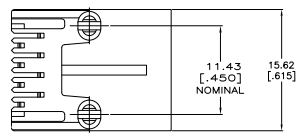
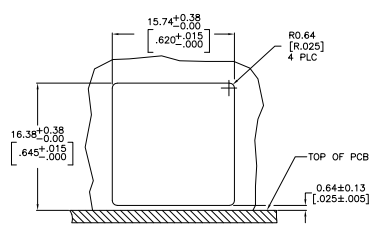
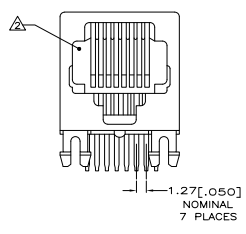
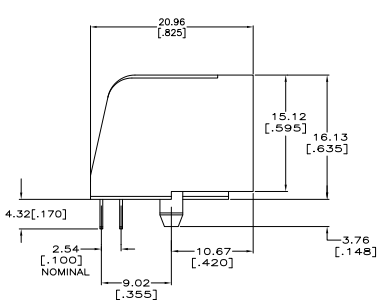


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REV	DATE	DESCRIPTION	BY	CHK	APP
AA	00				
B	02-07-2009				



RECOMMENDED PRINTED CIRCUIT BOARD
 LAYOUT
 COMPONENT SIDE SHOWN

- MATERIAL: HOUSING PBT POLYESTER, COLOR: BLACK. TERMINAL - 0.38 [0.14] THICK PHOS-BRONZE PLATED WITH 1.27µm [0.00050] MINIMUM THICK HARD GOLD IN LOCALIZED GOLD PLATE AREA AND 3.81µm [0.00150] MINIMUM THICK MATTE TIN IN SOLDER AREA OVER 1.27µm [0.00050] MINIMUM THICK NICKEL UNDERPLATE.
 - CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68 AND REA BULLETIN 345-81, PE-76 SPECIFICATION FOR MODULAR TELEPHONE HARDWARE.
 - ALL DIMENSIONS SHOWN ARE MAXIMUM UNLESS OTHERWISE SPECIFIED.
- ▲ BULK PACKAGED IN TRAY

PACKAGED	8	5520426-4
CONTACTS		PART NUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT.		DESIGNED BY: J. ATHAIA	DESIGNED BY: J. ATHAIA	DATE: 02/07/09	DATE: 02/07/09
DRAWN BY: J. WESTMAN		DESIGNED BY: J. WESTMAN	DESIGNED BY: J. WESTMAN	DATE: 02/07/09	DATE: 02/07/09
CHECKED BY: J. WESTMAN		DESIGNED BY: J. WESTMAN	DESIGNED BY: J. WESTMAN	DATE: 02/07/09	DATE: 02/07/09
APPROVED BY: J. WESTMAN		DESIGNED BY: J. WESTMAN	DESIGNED BY: J. WESTMAN	DATE: 02/07/09	DATE: 02/07/09
SEE NOTE 1		SEE NOTE 1	SEE NOTE 1	SEE NOTE 1	SEE NOTE 1
CUSTOMER DRAWING		DATE: 02/07/09	DATE: 02/07/09	DATE: 02/07/09	DATE: 02/07/09